

## REMARKS

Claims 1-8 have been rejected under 35 USC 103(a) as unpatentable over U.S. Patent Publication No. 2002/0047210 (Yamada) in view of U.S. Patent No. 6,894,386 (Poo).

Applicants respectfully traverse this rejection.

Claim 1 recites an adhesive layer bonding the supporting body to the front surface of the semiconductor chip. The Examiner agrees that no portion of Yamada teaches or suggests the claimed adhesive layer. See page 3 of the Action. To overcome this deficiency of Yamada, the Examiner contends that Poo's encapsulant layer 340 corresponds to the claimed supporting body and Poo's passivation layer 320 to the claimed adhesive layer. Applicants respectfully disagree.

Nothing in Poo states that Poo's passivation layer 320 is an adhesive layer as claimed. The only evidence the Examiner provides to support his contention is Poo's statement at column 5, lines 36-37, that "passivation layer 320 includes polyimide [sic]." Persons of ordinary skill in the art would have known that "polyimide," or polyimide, in semiconductor device applications provides mechanical support as a printed circuit board or a dielectric coating and does not act as an adhesive.

In Poo's device manufacturing process as described at column 4, line 55 - column 5, line 65, which was relied upon by the Examiner, once Poo's passivation layer 320, which the Examiner equates to the claimed adhesive layer, is formed to cover the wafer 300, the wafer covered with the passivation layer 320 is diced along saw street 305 using cutter 325. See column 5, lines 41-46, of Poo. Persons of ordinary skill in the art would have understood that an exposed and unprotected adhesive layer formed on a wafer would be significantly damaged when the wafer is diced, because the adhesive layer is exposed to the cutting liquid and the cutting debris which would adhere to the adhesive layer. Thus, Poo's passivation layer 320 made of "polyimide" cannot be and is not an adhesive layer as claimed because the use of such an adhesive layer as the passivation layer 320 would result in a device that has defects, i.e., debris and water, between the passivation layer 320 and the encapsulant layer 340.

Claim 5 recites substantially the same adhesive layer as claim 1. Thus, the rejection of claims 1-8 under 35 USC 103(a) over Yamada and Poo should be withdrawn because Yamada and Poo do not teach or suggest the claimed adhesive layer.

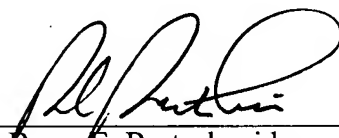
In light of the above, a Notice of Allowance is solicited.

In the event that the transmittal letter is separated from this document and the Patent and Trademark Office determines that an extension and/or other relief is required, applicants petition for any required relief including extensions of time and authorize the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to **Deposit Account No. 03-1952**, referencing Docket No. **606402017700**.

Respectfully submitted,

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